The Syfer X2Y Integrated Passive Component is a 3 terminal EMI chip device. The revolutionary design provides simultaneous line-toline and line-to-ground filtering, using a single ceramic chip. In this way, differential and common mode filtering are provided in one device. Capable of replacing 2 or more conventional devices, it is ideal for balanced lines, twisted pairs and dc motors, in automotive, audio, sensor and other applications.

Available in sizes from 0603 to 2220, these filters can prove invaluable in meeting stringent EMC demands.

Manufactured in the UK by Syfer Technology Limited under licence from X2Y attenuators LLC.

Specifications

Dielectric Electrical Configuration Capacitance Measurement Typical Capacitance Matching Temperature Rating Dielectric Withstand Volage

Insulation Resistance Termination Material

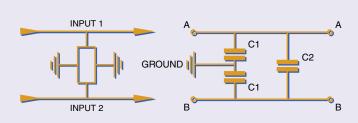
X7R or C0G/NP0 Multiple capacitance At 1000hr point Better than 5% -55°C to 125°C 2.5 x Rated Volts for 5 secs. Charging current limited to 50mA Max. 100Gohms or 1000s (whichever is the less) 100% matte tin over nickel

Advantages

- Replaces 2 or 3 capacitors with one device Matched capacitance line to ground on both lines
- Low inductance due to cancellation effect
- Differential and common mode attenuation
- Effects of temperature and voltage variation eliminated Effect of ageing equal on both lines High current capability

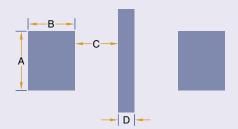
Applications

- Balanced lines and twisted pairs
- EMI Suppression on DC motors
- Sensor/transducer applications
- Wireless communications
- Audio
- CANBUS



Cilip						
Size	L	W	Т	L1	L2	
0603*	1.6±0.2 (0.063±0.008)	0.8±0.2 (0.03±0.008)	0.5±0.15 (0.02±0.006)	0.4±0.15 (0.016±0.006)	0.25±0.15 (0.010±0.006)	
0805	2.0±0.3 (0.08±0.012)	1.25±0.2 (0.05±0.008)	1.0±0.15 (0.04±0.006)	0.5±0.25 (0.02±0.01)	0.3±0.15 (0.012±0.006)	
1206	3.2±0.3 (0.126±0.012)	1.60±0.2 (0.063±0.008)	1.1±0.2 (0.043±0.008)	0.95±0.3 (0.037±0.012)	0.5±0.25 (0.02±0.01)	
1410	3.6±0.3 (0.14±0.012)	2.5±0.3 (0.1±0.012)	2 max. (0.08 max.)	1.20±0.3 (0.047±0.012)	0.5±0.25 (0.02±0.01)	
1812	4.5±0.35 (0.18±0.014)	3.2±0.3 (0.126±0.012)	2 max. (0.08 max.)	1.4±0.35 (0.06±0.014)	0.75±0.25 (0.03±0.01)	
2220	5.7±0.4 (0.22±0.016)	5.0±0.4 (0.2±0.016)	2.5 max. (0.1 max.)	2.25±0.4 (0.09±0.016)	0.75±0.25 (0.03±0.01)	

Recommended Solder Lands



	Difficusions filli (filciles)				
Chip Size	Α	В	C	D	
0603*	0.6 (0.024)	0.6 (0.024)	0.4 (0.016)	0.2 (0.008)	
0805	0.95 (0.037)	0.9 (0.035)	0.3 (0.012)	0.4 (0.016)	
1206	1.2 (0.047)	0.9 (0.035)	0.6 (0.024)	0.8 (0.03)	
1410	2.05 (0.08)	1.0 (0.04)	0.7 (0.028)	0.9 (0.035)	
1812	2.65 (0.104)	1.4 (0.055)	0.8 (0.03)	1.4 (0.055)	
2220	4.15 (0.163)	1.4 (0.055)	1.2 (0.047)	1.8 (0.071)	

Dimensions mm (inches)

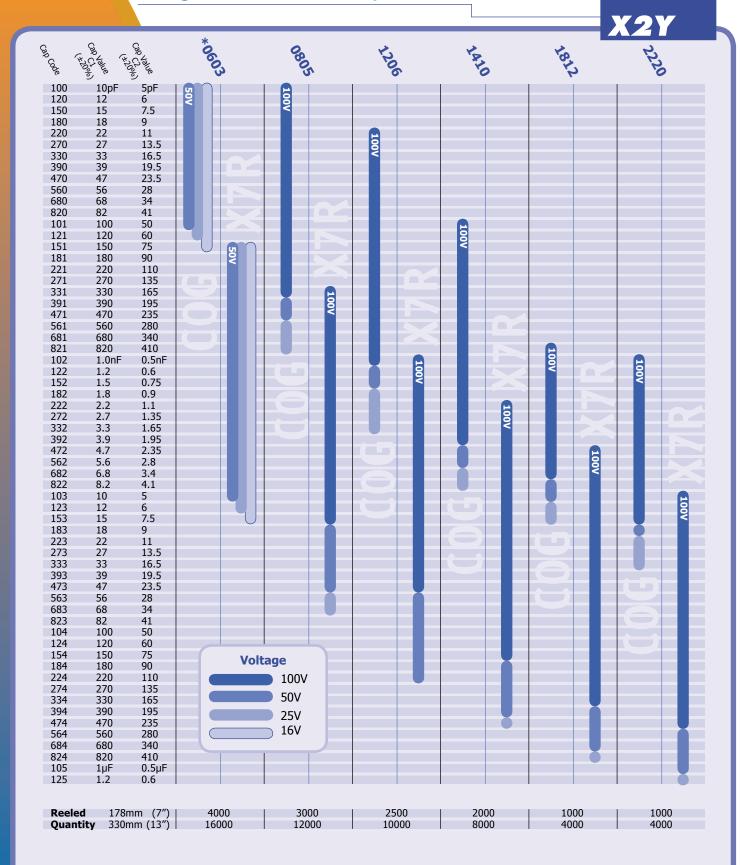
Insertion Loss Characteristics (common mode) Typical 50 ohm system

60 Insertion Loss (dB) 40 20 0.1 10 100 1000 Frequency (MHz)



The 0603 chip size is a development item. All technical information should be considered provisional and subject to change. Refer to Sales office.





notes

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The Syfer X2Y Integrated Passive Component has a unique internal architecture which provides unbeatable EMC performance for dual line data transmission.

INPUT 1
INPUT 2
INPUT 3
INPUT 4

CHIP CAPACITORS

A typical application for dual line data transmission would see a board layout using decoupling chip capacitors or 3 terminal feedthrough chips as shown in Fig 1.

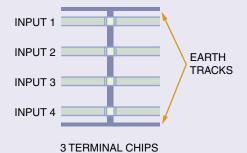


Fig 1

The Syfer X2Y Integrated Passive Component replaces decoupling capacitors or 3 terminal feedthrough chips on a 1 for 2 basis and provides line to line (differential mode) decoupling. Fig 2.

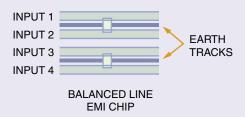
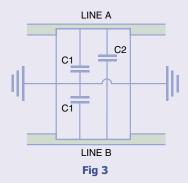


Fig 2

The internal structure furnishes a reduced inductance when compared to that of a conventional capacitor. This is a result of the novel internal electrode structure which inherently reduces the inductance by the cancellation effect of opposing currents in close proximity.

The capacitance line to ground (common mode) is closely matched due to the symmetry within the design. As the device includes line to ground capacitance for both lines, any temperature, ageing and voltage effects will have an equal influence on both lines therefore maintaining balanced decoupling.

The construction also allows a capacitance between lines as well as to ground as shown in Fig 3.



C2, the line to line capacitance, is half the line to ground capacitance thus providing coupling of high frequency interference between balanced lines.

Because the part acts as a decoupling device, the current limitations of a standard 3 terminal chip do not apply. The single line 3 terminal feedthrough chip carries the signal current through the very thin feedthrough electrodes within the device which have limited DC resistance and so can cause excessive heating, hence the maximum permissible current is often limited to around 300 mA for a 1206 device. The dual line 3 terminal chip is in by-pass across two lines and so is unaffected by high signal currents.

Table 1 offers a comparison of decoupling devices and demonstrates how the Syfer X2Y Integrated Passive Component extends the options for EMC circuit protection.

Component	Advantages	Disadvantages	Applications	
Chip capacitor	Industry standard	Requires 1 per line High inductance Capacitance matching problems	By-pass Low frequency	
3 terminal feedthrough	Feedthrough Lower Inductance	Current limited	FeedthroughUnbalanced linesHigh frequency	
Syfer X2Y Integrated Passive Component	 Very low inductance Replaces 2 (or 3) components Negates the effects of temperature, voltage and ageing Provides both common mode and differential mode attenuation 	 Not for unbalanced signal lines 	By-pass Balanced lines High frequency DC electric motors	
Table 1				

syfer.com

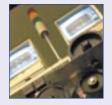
X2Y

Application Note

One of the significant features of this product is its extremely low inductance, making it particularly suitable for high speed digital applications and for reduction of common mode currents for power line applications. Inductance cancellation, due to the effect of opposing current flow across the device, results in a typical line to line inductance of around 100pH, with a corresponding line to ground inductance of 50pH.

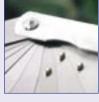
The Syfer X2Y Integrated Passive Component satisfies the need for high speed communications systems using balanced lines or twisted pairs offering low inductance (therefore high frequency operation), reduced board space, reduced component count and an unparalleled performance.

Ordering Information						
1206 J	100	0222	M	X	T	E03
Chip Size Reference 0603 0805 1206 1410 1812 2220	016 = 16 volts or 025 = 25 volts	Capacitance Expressed in picofarads (pF). First digit is 0. Second and third digits are significant figures of capacitance code. The fourth digit is number of zeros following. Example: 0222=2200pF.	Tolerance M= ±20%	Dielectric C = COG X = X7R	Packaging T = 178mm (7") reel R = 330mm (13") reel B = Bulk	Syfer X2Y Integrated Passive Component

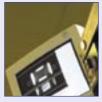








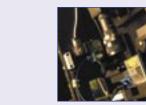
















- Syfer Technology are able to provide comprehensive applications and design in support.
- Technical and application papers are available on request from the Sales Office.
- For additional technical information, please visit either the Syfer website (www.syfer.com) or the X2Y Attenuators website (www.X2Y.com).

Manufactured in the UK by Syfer Technology Limited under licence from X2Y attenuators LLC.



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